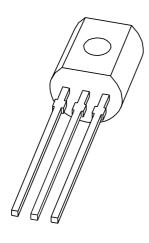
### DISCRETE SEMICONDUCTORS

# DATA SHEET



# MPSA56 PNP general purpose transistor

Product data sheet Supersedes data of 1999 Apr 27 2004 Dec 13



## PNP general purpose transistor

MPSA56

#### **FEATURES**

- Low current (max. 500 mA)
- Low voltage (max. 80 V).

#### **APPLICATIONS**

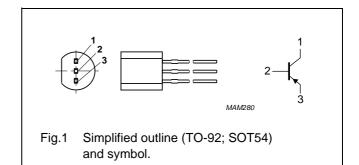
• General purpose switching and amplification.

#### **DESCRIPTION**

PNP transistor in a TO-92; SOT54 plastic package. NPN complement: MPSA06.

#### **PINNING**

PIN	DESCRIPTION			
1	collector			
2	base			
3	emitter			



#### **ORDERING INFORMATION**

TYPE NUMBER	PACKAGE				
TIPE NUMBER	NAME	ME DESCRIPTION VERS			
MPSA56	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54		

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	-80	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	-80	V
$V_{EBO}$	emitter-base voltage	open collector	_	-5	V
I <sub>C</sub>	collector current (DC)		_	-500	mA
I <sub>CM</sub>	peak collector current		_	-1	Α
I <sub>BM</sub>	peak base current		_	-200	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	_	625	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	ambient temperature		-65	+150	°C

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

# PNP general purpose transistor

MPSA56

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	note 1	200	K/W

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

#### **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	PARAMETER CONDITIONS		MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	$V_{CB} = -80 \text{ V}; I_E = 0 \text{ A}$	_	-50	nA
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; I_C = 0 \text{ A}$	_	-50	nA
h <sub>FE</sub>	DC current gain	$V_{CE} = -1 \text{ V; } I_{C} = -10 \text{ mA}$	100	_	
		$V_{CE} = -1 \text{ V; } I_{C} = -100 \text{ mA}$	100	_	
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_C = -100 \text{ mA}; I_B = -10 \text{ mA}$	_	-250	mV
$V_{BE}$	base-emitter voltage	$V_{CE} = -1 \text{ V; } I_{C} = -100 \text{ mA}$	_	-1.2	V
f <sub>T</sub>	transition frequency	$V_{CE} = -1 \text{ V}; I_{C} = -100 \text{ mA}; f = 100 \text{ MHz}$	50	_	MHz

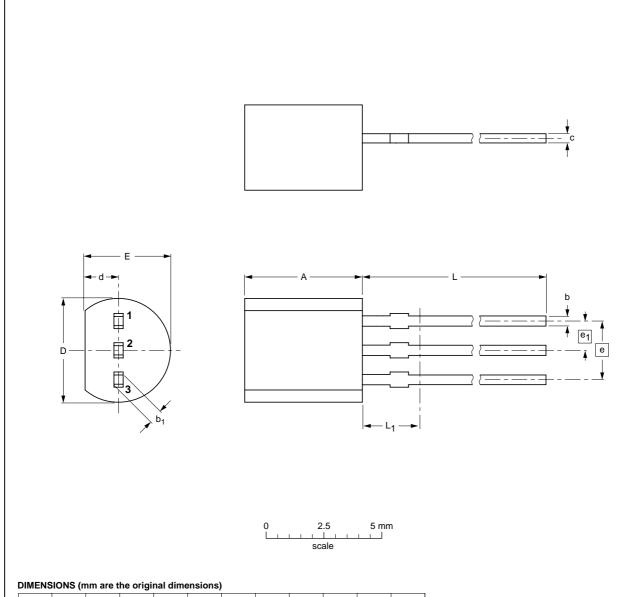
# PNP general purpose transistor

MPSA56

#### **PACKAGE OUTLINE**

#### Plastic single-ended leaded (through hole) package; 3 leads

SOT54



UNIT	Α	b	b <sub>1</sub>	С	D	d	E	е	e <sub>1</sub>	L	L <sub>1</sub> <sup>(1)</sup> max.	
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5	

#### Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE		REFER	EUROPEAN ISSUE DATE				
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT54		TO-92	SC-43A			<del>-04-06-28</del> 04-11-16	

#### PNP general purpose transistor

MPSA56

#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### **Notes**

- 1. Please consult the most recently issued document before initiating or completing a design.
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